SMAPPIC: Scalable Multi-FPGA Architecture Prototype Platform in the Cloud

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ABSTRACT
Traditionally, architecture prototypes are built on top of FPGA infrastructure, with two associated problems. First, very large FPGAs are prohibitively expensive for most people and institutions. Second, the burden of FPGA development adds to an already uneasy life of researchers, especially those who focus on software. Large designs that do not fit into a single FPGA exacerbate these issues even more. This work presents SMAPPIC — the first open-source prototype platform for shared memory multi-die architectures on cloud FPGAs. SMAPPIC leverages the OpenPiton/BYOC infrastructure and AWS F1 instances to make FPGA-based prototypes of System-on-Chips, processor cores, accelerators, cache subsystems, etc., cheap, scalable, and straightforward. SMAPPIC enables many use cases that are not possible or significantly more complicated in existing software and FPGA tools. This work has the potential to accelerate the rate of innovation in computer engineering fields in the nearest future.

CCS CONCEPTS
• Hardware → Simulation and emulation; Reconfigurable logic and FPGAs; • Computer systems organization → Multicore architectures; Heterogeneous (hybrid) systems.

KEYWORDS
Modeling, FPGA, cloud, multi-die, interconnect, multicore, heterogeneity

ACM Reference Format:

1 INTRODUCTION
The approaching demise of Moore’s Law [25] puts the task of optimizing computation on the shoulders of system-level researchers: computer architects, compiler engineers, operating system and runtime developers, etc. Correspondingly, the number of papers in the top venues in these fields has increased dramatically over the last 20 years [1–3]. One can imagine a future where all the advances in computation come purely from clever new techniques and features designed by these researchers. However, most of such work demands working on futuristic, currently nonexistent hardware. This highlights the importance of a cheap, fast, scalable, and easy-to-use prototyping infrastructure.

Traditionally, architecture prototypes are built on top of Field-Programmable Gate Array (FPGA) infrastructure. This approach has two significant associated problems. First, FPGA development is a complicated task that requires deep knowledge of not only Register Transfer Level (RTL) but also the details and physical constraints of the chosen FPGA platform. Many researchers (especially those who focus more on software aspects) would rather spend their time and effort on something closer to their interests. Second, FPGAs needed for large systems’ prototypes must be bought by researchers for a significant price (starting from $5000 or $20000 for a set of four) [62]. Therefore, independent researchers cannot afford to use FPGAs at all, and large entities cannot afford to scale out FPGA infrastructure, i.e., evaluate multiple systems in parallel or use multiple FPGAs for a single prototype.

Moreover, the end of Moore’s Law gradually slows down the transistor density scaling and forces designers to implement increasingly larger designs each year [33]. Correspondingly, prototypes are also becoming larger and no longer fit into a single FPGA. Partitioning prototypes across multiple FPGAs further exacerbates both price and complexity issues. Emulation systems like Synopsys Zebu [55] solve the complexity problem but only at the cost of even more expensive hardware.

The current COVID-19 pandemic makes FPGAs even less accessible. Working with an FPGA often requires physical access to the hardware, which can be unavailable due to pandemic restrictions like lockdowns and Work-From-Home orders. Moreover, due to the pandemic-induced chip shortage, purchasing FPGAs is challenging even with the necessary funds. For example, lead times for large FPGAs from Xilinx now exceed half a year [62].

However, FPGAs have debuted as offerings from multiple public cloud providers in the past five years, including Amazon Web Services (AWS) [19, 32, 43]. This development presents a unique opportunity for researchers to embrace FPGA prototyping or migrate their flow from existing on-premise solutions to cloud FPGAs, enabling them to run thousands of instances in parallel or to distribute large designs across multiple FPGAs for a modest price. Such a prototype also presents the opportunity to use large datasets available only in the cloud or have an FPGA prototype interacting with cloud-only services like complex Function-as-a-Service (FaaS) pipelines. Computer architecture, operating systems, and compilers...
classes can also use cloud FPGA platforms’ on-demand scale-out nature for educational purposes beyond what a single academic institution can purchase.

This paper presents Scalable Multi-FPGA Architecture Prototype Platform in the Cloud (SMAPPIC) – the first open-source\(^1\) prototype platform for shared memory multi-die architectures on cloud FPGAs. SMAPPIC is designed with three main goals: ease of use, cost-effectiveness, and scalability. They all are achieved through a modular, hierarchical, and parametrizable structure based on a cloud FPGA backend.

SMAPPIC is a ready-to-use solution that makes architectural FPGA prototyping easy and accessible to researchers from various computer science and computer engineering fields. Researchers do not need to be experts in FPGA development to implement their prototypes, and the modular design of SMAPPIC allows them to make RTL modifications with non-invasive changes. Moreover, many software studies can be performed by tuning built-in platform parameters without the need to change RTL code altogether. SMAPPIC’s cloud FPGA backend makes it accessible and cost-effective, allowing users to pay for infrastructure per hour.

Each prototype in SMAPPIC contains one or more separate nodes, where each node represents a single chip or die of the target system. Nodes can be distributed across multiple target FPGAs; they can be independent and represent separate systems or be merged with newly designed inter-node interconnect into one large system. SMAPPIC configurations are described in AxBxC notation, where A is the number of FPGAs in the prototype, B is the number of nodes per FPGA, and C is the number of tiles per node. Fig. 1 shows the example SMAPPIC hierarchies:

1. Fig. 1a shows a classic 1x1x12 configuration with a single prototype that implements one node in one FPGA.
2. Fig. 1b shows a cost-efficient 1x4x2 configuration. Such configuration allows modeling multiple systems with different parameters in one FPGA to optimize utilization and cost-efficiency.
3. Fig. 1c shows a 4x1x12 configuration. It represents a cache-coherent multi-node system with 4 large 12-core nodes.
4. Fig. 1d shows a 4x4x2 configuration. It represents a cache-coherent multi-node system with 16 small 2-core nodes.

We chose the BYOC/OpenPiton [10, 11] framework as SMAPPIC’s node foundation and AWS EC2 F1 instances as a target FPGA infrastructure. Together, they provide all the necessary features needed to achieve our design goals:

1. The BYOC framework provides a modular and configurable RTL model of a heterogeneous computing platform with Network-On-Chip (NoC) interconnect and scalable coherent cache subsystem inside each node. Various research groups have already integrated Ariane [65], OpenSPARC T1 [37], ao486 [39], PicoRV32 [60], AnyCore [17], BlackParrot [41] cores as well as NVDLA [34] and MIAOW GPU [8] accelerators into BYOC. These computational cores can be used out of the box without any modifications. Moreover, the Transaction Response Interface (TRI) allows for fast and easy integration of other new computation cores.

\(^{1}\)Source code: https://parallel.princeton.edu

Figure 1: SMAPPIC generates optimized prototypes for various targets. Configurations are denoted in AxBxC format, where A is the number of FPGAs, B is the number of nodes per FPGA, and C is the number of tiles per node.
Figure 2: F1 instances organization. F1 FPGA contains two partitions: Custom Logic (CL) and Hard Shell (HS). Users can fully customize CL; HS is fixed and provided by AWS. All communication with the host happens through HS, where requests and responses are converted from the host-FPGA PCIe connection to AXI4/AXI-Lite interfaces and back.

(2) AWS EC2 F1 instances provide infrastructure for cheap, scalable, on-demand FPGA prototyping. Four independent DRAM interfaces in F1 make it possible to pack up to four nodes into one FPGA. At the same time, the F1 instance’s ability to perform direct FPGA-to-FPGA communication through the PCIe interface makes SMAPPIC’s coherent inter-node interconnect possible.

There are many unique use cases that are impossible or significantly harder without SMAPPIC. We discuss some of them in this paper, including large-scale multi-node architecture modeling, accelerator evaluation and verification, hardware/software co-development, in situ studies of a custom architecture interaction with a cloud infrastructure, cost-efficient architecture modeling, remote work, education, and more.

Our contributions include:
- The first open-source prototype platform for shared memory multi-node architectures on cloud FPGAs
- The first open-source RISC-V multi-node system with unified memory
- The first open-source 48-core 64-bit RISC-V system with coherent memory
- The first demonstration of full-stack Linux running on a 48-core RISC-V system in NUMA mode
- The first comparison of architecture modeling methods in the cloud with respect to cost-efficiency
- Demonstration of custom prototype interacting with public cloud services

2 BACKGROUND

2.1 AWS EC2 F1 Infrastructure

AWS debuted EC2 F1 instances as an option in its public cloud in November 2016 as a way to offer its customers customizable acceleration capabilities. AWS currently offers three F1 instances: f1.2xlarge, f1.4xlarge, and f1.16xlarge; their parameters and prices are listed in Table 1. Overall, users can get up to 8 Xilinx VU9P [64] FPGAs inside one instance. Each hour of a single FPGA usage costs $1.65.

Figure 3: BYOC principal diagram (reproduced from [10]). BYOC has a modular open-source design, configurable cache subsystem, and a wide range of integrated cores and ISAs.

Fig. 2 shows a logical representation of F1 instances [42]. FPGAs in F1 are divided into two parts: 1) A Hard Shell (HS) provided by AWS that must be included in the final FPGA image, and 2) Custom Logic (CL), where developers have complete control over instantiated logic. Developers can access four DDR4 memory controllers and three AXI-Lite interfaces for logic configuration and management per FPGA. Data movement to/from the instance is performed through two AXI4 interfaces: one inbound and one outbound. The HS converts these AXI4 signals to/from PCIe Gen3 x16 connections. Depending on the target address, the outbound AXI4 request is routed to one of the FPGAs connected to the host or to the host itself.

The described setup is easy to recreate locally, given sufficient funds. Similar boards can be bought directly from Xilinx [62] or other vendors [12]. HS uses Xilinx XDMA IP under the hood, which is provided with each copy of Xilinx Vivado tools [63]. However, we estimate that the upfront cost of a similar system with a single FPGA (including server, FPGA, and FPGA memory) is about $8000, which can be too large of an investment for many researchers, especially if sporadically used.

2.2 BYOC and OpenPiton

BYOC [10] is a hardware framework for heterogeneous-ISA research. It supports the connection of cores with different ISAs and microarchitectures as well as accelerator integration. The high-level design of BYOC is shown in Fig. 3.

BYOC is built on top of OpenPiton [9] framework and Piton processor [31] and provides a modern, tiled manycore design with a cache coherence protocol and a Network-on-Chip (NoC) interconnect scalable to up to 500 million cores. BYOC’s cache subsystem is configurable and allows choosing different cache sizes and associativities. Users can select one of the ten provided core models. Notably, the framework already integrates Ariane [65], AnyCore [17], BlackParrot [41], OpenSparcT1 [37], PicoRV32 [60], and ao486 [39] cores. If this choice is not enough for the users, they can choose to connect their design using the Transaction Response Interface (TRI).

TRI is the gateway between a core and the central part of BYOC: its memory subsystem (see Fig. 3). This interface and BYOC Private Cache (BPC) were designed to isolate cores from details of
the coherence protocol in the underlying cache subsystem, thereby simplifying the integration of new compute units (cores) into BYOC. BPC can work as either a private L1 or L2 cache. BPCs are interconnected with each other and slices of distributed shared last-level cache (LLC) through three NoCs. The LLC also uses the NoCs to interact with the memory controller and peripherals, all located inside the chip.

The BYOC framework has an open-source codebase and is written in Verilog and SystemVerilog. This modular and configurable design makes it an excellent platform for experimenting and developing new hardware/software features; SMAPPIC leverages it to provide the same features in its nodes. At the same time, BYOC provides only limited FPGA prototyping capabilities without multi-node support.

3 ARCHITECTURE

A SMAPPIC prototype consists of one or several nodes; each node represents a single chip or die of the target system. Nodes can be independent of each other and implement separate instances of the prototyped design, or they can be connected with SMAPPIC’s specially designed inter-node interconnect to build a prototype of a single large shared memory multi-node system. We measured the inter-FPGA round-trip latency on the PCIe bus in an F1 instance to be about 1250 nanoseconds. At a typical FPGA frequency of around 100 MHz, this latency equals 125 cycles, which is the same order of magnitude as the inter-socket latency in a typical multi-socket system. Therefore, a multi-node system can be modeled either by putting all nodes into one FPGA or by distributing nodes across multiple FPGAs.

The nodes in our implementation are separate BYOC instances. However, the inter-node interconnect does not rely on any fundamental properties of BYOC, and BYOC can be replaced with any node model with multi-node capabilities. We chose BYOC because it strengthens SMAPPIC’s advantages: modularity, configurability, and ease of use.

3.1 Inter-node Interconnect

SMAPPIC’s inter-node interconnect is designed to make large-scale multi-node prototypes possible. It binds together nodes located in the same FPGA and different FPGAs. To achieve this, the interconnect encapsulates traffic between nodes into AXI4 write requests. This solution allows connecting nodes on the same FPGA using the AXI4 crossbar and nodes on different FPGAs using the AXI4-PCIe transducer provided in Hard Shell. The encapsulation does not change the traffic and does not significantly rely on packet structure, and the BYOC can be replaced with any other node model with inter-node capabilities fairly easily.

Fig. 4 shows the high-level design of SMAPPIC in a 4x1x12 configuration. Each node is located in its own FPGA and communicates with other nodes through inbound and outbound AXI4 interfaces. We will go through an example of what happens during a BPC cache miss to show the functionality of SMAPPIC. Blue numbers and lines in Fig. 4 schematically show the sequence of events and NoC communication.

- Stage 1: a core on node 0 in tile 3 does a memory read that causes L1 and BPC cache misses. BPC issues a read request to the cache line’s home LLC slice in this case. The homing mechanism in BPC decides where the cache line’s home is. The original BYOC design supports multi-chip configuration through a special hardware/software mechanism called Coherence Domain Restriction [22]. Unlike BYOC, SMAPPIC’s

Table 1: Available AWS EC2 F1 instances [44].

<table>
<thead>
<tr>
<th>Instance</th>
<th>f1.2x1</th>
<th>f1.4x1</th>
<th>f1.16x1</th>
</tr>
</thead>
<tbody>
<tr>
<td>#vCPUs</td>
<td>8</td>
<td>16</td>
<td>64</td>
</tr>
<tr>
<td>Host Memory</td>
<td>122 GB</td>
<td>244 GB</td>
<td>976 GB</td>
</tr>
<tr>
<td>Storage</td>
<td>470 GB</td>
<td>940 GB</td>
<td>3760 GB</td>
</tr>
<tr>
<td>#FPGAs</td>
<td>1</td>
<td>2</td>
<td>8</td>
</tr>
<tr>
<td>FPGA Memory</td>
<td>64 GB</td>
<td>128 GB</td>
<td>512 GB</td>
</tr>
<tr>
<td>Pricing</td>
<td>$1.65/hr</td>
<td>$3.30/hr</td>
<td>$13.20/hr</td>
</tr>
<tr>
<td>Hardware price</td>
<td>≈ $8000</td>
<td>≈ $16000</td>
<td>≈ $64000</td>
</tr>
</tbody>
</table>

Figure 4: SMAPPIC in 4x1x12 configuration. Inter-node NoC packets are first routed towards Tile 0, then pushed out in the northbound direction into the inter-node bridge, where they are encapsulated into AXI4 requests and tunneled in the PCIe bus to other nodes in other FPGAs.
homing mechanism was changed to distribute cache lines across all nodes in the system and work out of the box without software support. The read is local if the cache line’s home slice is located in the same node. However, in our example, the core is in node 0, and the home slice is in node 3, making this request inter-node.

• Stage 2: NoC routers are programmed to route inter-node packets into tile 0, then in the northbound direction, where they leave the node and enter the inter-node bridge specifically designed to encode NoC packets into outgoing AXI4 requests and vice versa.

• Stage 3: A NoC packet is encapsulated into AXI4 write requests. The request’s address encodes the destination node ID, source node ID, and valid bits for flits encoded in write data. To guarantee the absence of deadlocks in the system, the NoC must have credit-based flow controls. To return credits, the sending side periodically issues an AXI4 read request to the receiving side and gets the number of returned credits in response.

• Stages 4-5: The request is converted into PCIe transfer inside HS and sent to the other FPGA. This PCIe traffic goes directly from FPGA to FPGA and does not use the host CPU.

• Stages 6-7: The response from the home slice is sent back to node 0 in the form of another PCIe transfer.

• Stage 8: The PCIe transfer is converted into an AXI4 request inside HS.

• Stage 9: An AXI4 request is decoded inside the inter-node bridge. The valid bits are taken from the request address, and NoC flits are taken from the request data. The request’s address also contains the source node-ID, which is used for credit accounting. If the inter-node bridge gets an AXI4 read request, it returns the credits in response.

• Stage 10: Response is routed back to the original core in tile 3 on node 0.

3.2 Memory Interfaces

The F1 infrastructure provides developers access to up to four DRAM interfaces. Developers are expected to use AXI4 interfaces for read and write requests, and BYOC’s original memory controller is incompatible with this protocol.

To manipulate the memory interfaces, we designed a NoC-AXI4 memory controller that transduces requests from the native NoC protocol to the AXI4 interface and sends responses back via the NoC to the requesting tile. Its high-level design is shown in Fig. 5. Incoming requests from the NoC are first deserialized and then forwarded to the management module. There, requests are buffered to enable non-blocking functionality and higher throughput. Requests are then steered into the corresponding engine: memory reads into the read engine and memory writes into the write engine. The engines assign an AXI4-ID to each request and save the Miss Status Handling Register (MSHR), the ID-MSHR mapping, the origin of the request in the system, and other miscellaneous information. The request’s address and data (in the case of a write) are then aligned to a 64-byte boundary to fulfill the AXI4 protocol requirements. Upon response arrival, ID-MSHR mapping is used to restore the initial request’s MSHR. If it is a read response and the original request is smaller than 64 bytes, the necessary portion of bytes is selected. The response and data (in case of a read) are then pushed into the NoC serializer, after which they leave the memory controller.

3.3 RISC-V Interrupt Controller

Another essential part of SMAPPIC is its RISC-V interrupt controller. We want to make the transition to our platform as seamless for researchers as possible. With the growing popularity of RISC-V in the community, it was important for us to have this functionality available out of the box.

In the RISC-V specification [5], cores are notified about pending interrupts by asserting a wire going straight from the interrupt controller into the core. This specification lacks scalability because a) in the case of a manycore system, a wire goes across the whole node and uses significant routing resources and affects the timing of the design, and b) in the case of a multi-node system, it is difficult or impossible to route a wire across node boundary.

To deal with this problem, we designed an interrupt packetizer and depacketizer. Fig. 6 shows their functionality. The interrupt packetizer scans the interrupt controller’s outputs, and when they
Table 2: Prototyped System Parameters

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>Instruction set</td>
<td>RISC-V 64-bit</td>
</tr>
<tr>
<td>Operating system</td>
<td>Linux v5.12</td>
</tr>
<tr>
<td>Frequency</td>
<td>100 MHz</td>
</tr>
<tr>
<td>Core</td>
<td>Ariane</td>
</tr>
<tr>
<td>Core pipeline</td>
<td>In-order, 6 stages</td>
</tr>
<tr>
<td>Branch history table entries</td>
<td>128</td>
</tr>
<tr>
<td>ITLB entries</td>
<td>16</td>
</tr>
<tr>
<td>DTLB entries</td>
<td>16</td>
</tr>
<tr>
<td>L1D cache</td>
<td>8 KB, 4 ways</td>
</tr>
<tr>
<td>L1I cache</td>
<td>16 KB, 4 ways</td>
</tr>
<tr>
<td>BPC cache</td>
<td>8 KB, 4 ways</td>
</tr>
<tr>
<td>LLC cache slice</td>
<td>64 KB, 4 ways</td>
</tr>
<tr>
<td>DRAM latency</td>
<td>80 cycles</td>
</tr>
<tr>
<td>Inter-node round-trip latency</td>
<td>125</td>
</tr>
</tbody>
</table>

change, it notifies the appropriate core about the change by sending a NoC packet. On the core side, the interrupt depacketizer sniffs the network traffic, and when an interrupt packet arrives, the interrupt wires are asserted or deasserted depending on the packet contents.

3.4 I/O Interfaces

3.4.1 UART and Serial Interfaces. UART is an essential interface for SMAPPIC: it is used for all the external interactions like loading tests into memory and console I/O operations. However, the F1 infrastructure does not provide a UART interface to the developer.

To tackle this issue, we encapsulate UART into the AXI-lite protocol and use one of the available AXI-Lite interfaces in F1 to further tunnel data from the FPGA to the host. The UART to AXI-Lite conversion is done with a Xilinx UART16550 IP [61] included with Xilinx Vivado. Further inside the host system, we developed a new program that creates a virtual serial device and tunnels data from the PCIe driver into this virtual serial device.

We instantiate two UART devices inside each BYOC instance: one with the standard baud rate of 115200 bits/second for console interactions/instance management and one with an “overclocked” transmission rate of around 1 Mbit/second for data transmission. We used the overclocked device to connect the prototype to the Internet using the standard modem connection utility pppd.

3.4.2 Virtual SD Card. Like many datacenter FPGAs, the F1 FPGA does not have an SD card slot. However, BYOC requires an SD card controller to be able to provide a filesystem and run Linux. To solve this problem, we introduce the notion of a “virtual device” into SMAPPIC. We call a device virtual if it does not physically exist in the system; all requests to this device are instead forwarded into the SMAPPIC system’s main memory. Virtual devices provide only the functionality of the original device and do not model performance properly.

Since F1 lacks an SD card slot, we make the device virtual and map it into the top half of the FPGA’s DRAM; the remaining bottom half is used for the prototype’s main memory. For SD card initialization, we wrote a specialized Linux driver that is run on the host system. It performs the writes to the addresses inside the FPGA’s PCIe address space, and these writes eventually appear on the FPGA’s inbound AXI4 bus. This way, we can inject NoC flits inside the system. In particular, we can inject NoC packets that target the prototype’s memory controller and perform writes in the SD card region of memory.

3.5 Modeling Off-node Interfaces

The node’s interaction with the outside world cannot be mapped into FPGA gates. This includes inter-node communication, memory operations, input/output (I/O) operations, network operations, etc. To combat this modeling challenge, we include a traffic shaper with configurable bandwidth and latency in the inter-node bridge and memory controller. This solution provides performance models of interconnect and memory interfaces in addition to the functional models described above. I/O operations are modeled only functionally in SMAPPIC.

4 SMAPPIC USE CASES

This section describes our vision of how SMAPPIC can be employed for various problems.

4.1 Large-Scale Multi-node Architecture Modeling

In our first example, we build an FPGA prototype of a 64-bit cache-coherent RISC-V multi-node system with a total of 48 cores. Using this prototype, we run a full-stack Linux operating system and evaluate its’ implementation of NUMA mode in the RISC-V architecture.

![Figure 7: Inter-core latencies in multi-node prototype in cycles. There are four clearly visible NUMA domains in the system. Round-trip latency inside one domain is about 100 cycles, and across domains – 250 cycles, 2.5 times higher.](image-url)
We use the integrated Ariane core in this example. SMAPPIC makes synthesizing the FPGA prototype straightforward: the user simply specifies the preferred core type, the number of tiles per node, the number of ndoes per FPGA, and the number of FPGAs. As an example, we create a prototype with a 4x1x12 configuration: four FPGAs, one node per FPGA, and 12 cores per node for a total of 48 Ariane cores. Fig. 2 shows the parameters of the prototyped system. The FPGA image generation takes about 2 hours on a desktop machine equipped with an Intel Core-i9 9900K CPU and requires about 32 GB of memory. Final postprocessing is done by AWS in their datacenter and takes another 2 hours. Loading the bitstream into FPGA takes about 10 seconds.

As a part of this case study, we run the full-stack Linux kernel in the generated prototype. The Linux kernel works out of the box in SMAPPIC. Non-uniform memory access (NUMA) mode has been available for RISC-V platforms since release 5.12, and since our setup has NUMA properties, we enabled it in the kernel configuration. The software reads NUMA parameters from the device tree during the boot process.

The first metric of interest for us is the communication latency between cores. Fig. 7 shows the heatmap of round-trip latencies between different cores in the system in cycles. The locations of the four NUMA nodes are clearly visible in this chart: cores on the same node have round-trip latency of about 100 cycles, and round-trip latency for cores on different nodes is about 250 cycles, 2.5 times higher than intra-node. This number is roughly the same for multi-socket Intel server platforms [21], which validates our idea of modeling multi-node systems with multi-FPGA setups. The inter-node link latency can be adjusted to represent systems with a slower interconnect, e.g., Ampere Altra [4].

We then evaluate the real-world performance of our prototype with an integer sorting benchmark from the NAS parallel benchmark (NPB) suite [7]. The benchmark uses a parallel bucket sorting algorithm to sort a 134-million-long array of integers (NPB’s class C input size). Fig. 8 shows the performance scaling with the number of cores with Linux NUMA mode on versus off. NUMA mode reduces runtime by 1.6-2.8 times depending on the number of threads. The difference is especially large with a high thread count; memory allocation becomes even more critical in this situation because of the large volume of inter-node communication and associated congestion. We also compared the scaling characteristics of the system with a similar multi-socket server setup from Intel. We saw a similar dynamic going from low thread count to full system usage.

Fig. 9 shows the same benchmark run in the same system, but this time we fix the number of threads to 12 and pin them to either 1, 2, 3, or 4 active nodes using the taskset utility to study how much suboptimal thread allocation hurts performance. Distributing threads among more nodes in NUMA mode leads to higher average memory access latency and slightly higher runtime. Interestingly, with NUMA mode disabled, the situation is reversed, and the performance slightly increases when cores are spaced further apart. We think that this happens because, with more nodes involved, there is a higher chance that at least some of the threads and application data are collocated on the same node.

The studies shown in this section are not possible on any simulator or emulator currently available to researchers. Only the SMAPPIC prototype can model benchmark runs in a large NUMA system running full-stack Linux at speeds around 100 MHz.

### 4.2 Accelerator Verification and Evaluation

SMAPPIC is a valuable framework for accelerator development. It includes tools for easy accelerator integration into the node’s architecture. Users can employ provided coherence tools to enable fine-grained interaction between the accelerator and the rest of the system. Superior speeds of FPGA emulation allow evaluating and verifying the accelerator with much larger input datasets than possible with purely software tools.
As an example, we built a prototype of a CPU with an integrated Gaussian Noise Generator (GNG) accelerator [28] from the OpenCores project [36]. Gaussian noise is widely used in communication channel testing, molecular dynamics simulation, and financial modeling [27]. The accelerator generates noise using the random numbers from the Tausworthe Generator [59]. It took around 1.5 hours of a graduate student’s work to do the initial integration and debugging. We use a SMAPPIC 1x1x2 configuration for simplicity, but users can quickly scale this prototype by only changing command line options passed to build scripts. Tile 0 contains the Ariane core, and tile 1 contains the GNG.

To fetch a new number from the GNG, Ariane issues a non-cacheable load to the accelerator’s memory address. We develop and study two integration schemes: base and optimized. In the base scheme, each non-cacheable load returns a single 16-bit number. In the optimized scheme, the load returns two or four 16-bit numbers packed into one 32-bit or 64-bit integer respectively. The optimization replaces multiple fetch operations with only one and reduces the number of needed loads.

After the prototype is built, users can easily evaluate and verify the accelerator with SMAPPIC’s built-in machinery. For illustrative purposes, we compare the accelerator’s performance with the software implementation executed in Ariane. We execute two benchmarks on top of Linux. Benchmark A (“Noise generator”) generates 64 MB of noise to compare software and hardware GNG implementations. Benchmark B (“Noise applier”) converts generated noise into 8-bit integers and applies it to a 32 MB long sequence to compare two implementations in a real-life scenario.

Fig. 10 shows performance results. The accelerator significantly decreases benchmarks’ execution times, especially when it combines multiple number fetches into one request. The performance difference is smaller in benchmark B because less of the execution time is accelerated here. The whole process of accelerator evaluation took about one graduate student’s workday from start to end.

As an example, we built a prototype of a CPU with an integrated Gaussian Noise Generator (GNG) accelerator [28] from the OpenCores project [36]. Gaussian noise is widely used in communication channel testing, molecular dynamics simulation, and financial modeling [27]. The accelerator generates noise using the random numbers from the Tausworthe Generator [59]. It took around 1.5 hours of a graduate student’s work to do the initial integration and debugging. We use a SMAPPIC 1x1x2 configuration for simplicity, but users can quickly scale this prototype by only changing command line options passed to build scripts. Tile 0 contains the Ariane core, and tile 1 contains the GNG.

To fetch a new number from the GNG, Ariane issues a non-cacheable load to the accelerator’s memory address. We develop and study two integration schemes: base and optimized. In the base scheme, each non-cacheable load returns a single 16-bit number. In the optimized scheme, the load returns two or four 16-bit numbers packed into one 32-bit or 64-bit integer respectively. The optimization replaces multiple fetch operations with only one and reduces the number of needed loads.

After the prototype is built, users can easily evaluate and verify the accelerator with SMAPPIC’s built-in machinery. For illustrative purposes, we compare the accelerator’s performance with the software implementation executed in Ariane. We execute two benchmarks on top of Linux. Benchmark A (“Noise generator”) generates 64 MB of noise to compare software and hardware GNG implementations. Benchmark B (“Noise applier”) converts generated noise into 8-bit integers and applies it to a 32 MB long sequence to compare two implementations in a real-life scenario.

Fig. 10 shows performance results. The accelerator significantly decreases benchmarks’ execution times, especially when it combines multiple number fetches into one request. The performance difference is smaller in benchmark B because less of the execution time is accelerated here. The whole process of accelerator evaluation took about one graduate student’s workday from start to end.
While there are many ways to model new architectures, modeling with AWS Lambda and S3 services. Fig. 12 shows the built pipeline. The incoming HTTP request goes through the following series of events:

1. The HTTP request enters the AWS Lambda function. The function acts as a gateway from the Internet to the private network. It redirects requests to the Nginx web server running on the SMAPPIC prototype.
2. The web server guides the request through the Common Gateway Interface (CGI) into the PHP script executed in the prototype alongside the web server.
3. The script fetches the data from the AWS S3 service.
4. The script attaches the current time to the data and returns it as a response to the web server.
5. The web server returns the response back to the Lambda function.
6. The function returns the response back to the original client.

This workflow presents a unique opportunity for researchers to integrate their custom design into a massive warehouse-scale datacenter and test its behavior and performance while interacting with complex cloud services. It enables the researchers to run RISC-V in the cloud and Internet with AWS’s vast APIs and observe the execution details directly inside the machine.

4.4 In Situ Studies of Custom Architecture Interaction with Cloud Infrastructure

While there are many ways to model new architectures, modeling their interactions with existing cloud infrastructure can be challenging. Researchers that study custom cloud architectures would greatly benefit from the ability to integrate the new hardware directly into a datacenter setting. SMAPPIC makes this task a lot easier because the prototype is located in the cloud, runs full-stack SMP Linux, and supports network connections via its serial interfaces. This aspect allows users to transform their custom architectures into first-class citizens inside the AWS infrastructure.

To prove this, we build a cloud pipeline that includes a SMAPPIC 1x1x4 prototype and multiple AWS services. The prototype executes the Nginx web server and PHP backend script, as well as interacts with AWS Lambda and S3 services. Fig. 12 shows the built pipeline. The incoming HTTP request goes through the following series of events:

1. The HTTP request enters the AWS Lambda function. The function acts as a gateway from the Internet to the private network. It redirects requests to the Nginx web server running on the SMAPPIC prototype.
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### Table 3: Requirements for host machines and cheapest suitable AWS EC2 instances [44].

<table>
<thead>
<tr>
<th></th>
<th>Sniper</th>
<th>gem5</th>
<th>Verilator</th>
<th>SMAPPIC &amp; FireSim</th>
</tr>
</thead>
<tbody>
<tr>
<td>#vCPUs</td>
<td>2</td>
<td>1</td>
<td>1</td>
<td>1</td>
</tr>
<tr>
<td>Memory (GB)</td>
<td>8</td>
<td>64</td>
<td>8</td>
<td>8</td>
</tr>
<tr>
<td>FPGA sizes (GB)</td>
<td>0</td>
<td>0</td>
<td>0</td>
<td>1</td>
</tr>
<tr>
<td>Instance</td>
<td>13.m</td>
<td>r5.2xl</td>
<td>13.m</td>
<td>f1.2xl</td>
</tr>
<tr>
<td>Price/hr</td>
<td>$0.04</td>
<td>$0.45</td>
<td>$0.04</td>
<td>$1.65</td>
</tr>
</tbody>
</table>

(1) The HTTP request enters the AWS Lambda function. The function acts as a gateway from the Internet to the private network. It redirects requests to the Nginx web server running on the SMAPPIC prototype.
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### 4.5 Cost-Efficient Architecture Modeling

In Sec. 4.1 we demonstrate that SMAPPIC is a valuable tool for large-scale architecture modeling. However, SMAPPIC also shows superior cost-efficiency among other modeling tools in the cloud. We compare the cost of modeling a similar 64-bit RISC-V system with different tools to demonstrate this. We use Sniper [14] as an example of a parallel simulator, gem5 [30] as an example of a cycle-level simulator, and Verilator [51] as an example of an RTL simulator. We also compare our work against another cloud FPGA tool, FireSim [24]. We use two FireSim configurations: 1) without network simulation and with one quad-core RocketChip instance, and 2) supernode configuration with network simulation and with four single-core RocketChip instances on one FPGA. We want to compare with the most cost-efficient FireSim configuration as measured by running benchmarks.

We execute benchmarks on a real RISC-V chip SiFive Freedom U740 SoC [46], part of the HiFive Unmatched [47] development platform, to get baseline results when running benchmarks in real RISC-V silicon.

We use a SMAPPIC prototype in a 1x1x2 configuration without an inter-node interconnect. This configuration allows us to model four independent prototypes inside one FPGA and significantly improves the cost-efficiency of SMAPPIC. The studied system parameters are listed in Table 2. All other tools were configured to model systems...
as similar to ours as possible. It is worth noting that all of the tools below are configured to use RISC-V workloads, except Sniper. Sniper has had initial support for RISC-V since version 7.3 [50], but it could not run RISC-V benchmarks out of the box or after we attempted to find and fix the problem. Therefore, we run Sniper with the X86-64 version of benchmarks. We do not expect this to affect our results significantly. Our target benchmark suite is SPECint 2017 with the “test” input size for simplicity. We could not run the benchmark perlbench on Sniper because it does not support forks inside executing workloads.

For each of the studied tools, we find the smallest and cheapest suitable instance in AWS EC2 offerings and then use its price per hour to calculate the cost of benchmark execution. Our minimal instance selections are described in Table 3.

The main limiting factor of software tools is the amount of memory the host instance has: Sniper needs at least 8 GB for proper functioning, and most of the gem5 runs could fit into a 64 GB allocation. However, two of the benchmarks required even more memory. For example, the gem5 run with the mcf benchmark completes only on a host with 350 GB of memory.

Modeling costs are shown in Fig. 13. As we expected, SMAPPIC shows the best cost-efficiency among other approaches. The main reason is its ability to allocate multiple prototype instances in a single FPGA and the high frequency provided by direct RTL-to-gate mapping. gem5 shows the worst results with 4-5 orders of magnitude higher cost than other tools because of its large memory requirements and long execution time. For this reason, we did not include gem5 results in the chart.

Compared to a single-node FireSim configuration, SMAPPIC shows about four times better cost-efficiency. Single-node FireSim and SMAPPIC have similar frequencies. However, SMAPPIC models four separate instances in parallel on one FPGA, whereas FireSim models only one. Similar to SMAPPIC, supernode FireSim puts four systems into one FPGA but still shows worse results because of its lower frequency.

For the sake of completeness, we also compare Verilator with SMAPPIC. In our small “Hello World” example, the Verilator simulation takes 65 seconds, and SMAPPIC finishes in 4ms. Based on data from Table 3 we can derive that SMAPPIC is about 1600 times more cost-efficient. Such a significant advantage makes a big difference in design verification.

As mentioned in Section 2.1, researchers can avoid using cloud infrastructure for FPGA prototypes and purchase similar hardware for on-premise usage instead. Our estimates on the price of similar servers with similar FPGA boards are shown in Table 1.

Based on these estimates and F1 instance pricing, we can compare the costs of using cloud and on-premises FPGA prototypes. Results are shown in Fig. 14.

Given the same prototype configuration running in both cases, it takes more than 200 days of continuous modeling to justify buying a private FPGA setup and using it on-premises. We consider this scenario possible only for huge research groups where such hardware will be shared between many users. However, even in such cases, the burden of proper hardware management and lack of ability to scale modeling makes the cloud option more preferable.

4.6 Remote Work

Using a cloud setup might be the only option during unexpected workflow disruptions like the current COVID-19 pandemic. In the last year and a half, together with our collaborators from other institutions, we finished two large chip tapeouts. These chips are based on heterogeneous architectures with multiple accelerators and complex interactions through a coherent cache subsystem. Such chip parameters require extensive design testing with real, large workloads and driver-controlled accelerators running under a full-stack operating system.

In such conditions, SMAPPIC was the only realistic option to perform design verification. RTL simulators do not have high enough performance to make the modeling of complete real system (with OS) workloads possible. At the same time, physical FPGA access was not available due to the Work-From-Home order.

After we finished the initial integration of accelerators, the prototype and all of its functionality worked out of the box. The cloud nature of SMAPPIC allowed us to launch multiple instances and work in parallel while being physically distributed in many different time zones. We found two critical bugs inside the accelerators.
themselves, one bug inside the RISC-V interrupt controller, and one problem with the interfacing of an accelerator and TRI interface.

4.7 Using SMAPPIC for Education

The value of using FPGAs in teaching architecture classes has been noted by multiple educators [35, 52]. However, before the era of cloud FPGAs, educational institutions could afford only limited use of FPGAs in classes. SMAPPIC is a potent tool for overcoming this problem. With a proper management tool, educators can use SMAPPIC to launch hundreds of instances on-demand and pay only for the time students actually use FPGAs for their assignments or projects. SMAPPIC is one of the tools used for final projects by students taking the computer architecture class at our institution this year.

4.8 Platform Limitations

Even though SMAPPIC allows for many unique use cases that are not achievable with other tools, there are a couple of factors to consider before choosing it as a modeling platform.

First, while SMAPPIC provides other parametrized model of a typical tiled multicore architecture with NoC and directory coherence, there are only a couple of provided fixed core models. For example, all case studies in this section used the Ariane core: an in-order core with a single-issue pipeline which may not be representative of large-core out-of-order designs. Users have two options on how to approach this limitation.

1. Provide the RTL design of their own custom core, use the functionality provided by the BYOC framework and TRI interface, and integrate it into the SMAPPIC model. In this case, the modeling results will be more accurate and represent the real system. However, this option requires some effort from the user.

2. Use one of the core models provided by SMAPPIC out of the box. This option requires less effort, but the modeling results will not represent the final target system exactly if its core differs from the core chosen in SMAPPIC. Nevertheless, we think this option is valuable for researchers who are more focused on obtaining qualitative results or care more about the interactions in the system as a whole. For example, this option is useful for studying the interaction between the cores and the integrated accelerators.

Another factor to consider when choosing SMAPPIC for research is the physical constraints of the FPGA infrastructure:

1. There is a finite number of gates per FPGA; this restricts the amount of logic that can be allocated per prototype and its frequency. For example, F1 FPGAs can fit at most 12 Ariane tiles at 75 MHz frequency. Table 4 shows various possible SMAPPIC setups. All configurations use core parameters from Table 2.

2. Each F1 FPGA contains only four memory slots, and each node in SMAPPIC has a separate memory controller. This requirement puts a cap of at most four nodes per FPGA in SMAPPIC.

3. Only four FPGAs in the F1 instance are connected with low-latency PCIe links. Therefore, one SMAPPIC prototype can include at most four FPGAs.

Table 4: SMAPPIC configurations with frequencies and LUT utilizations. Configurations are shown in BxC format, where B is the number of nodes per FPGA, and C is the number of tiles per node. Tile parameters are listed in Table 2.

<table>
<thead>
<tr>
<th>Configuration</th>
<th>Frequency</th>
<th>LUT Utilization</th>
</tr>
</thead>
<tbody>
<tr>
<td>1x12</td>
<td>75 MHz</td>
<td>97%</td>
</tr>
<tr>
<td>1x10</td>
<td>100 MHz</td>
<td>83%</td>
</tr>
<tr>
<td>2x4</td>
<td>100 MHz</td>
<td>73%</td>
</tr>
<tr>
<td>2x5</td>
<td>75 MHz</td>
<td>88%</td>
</tr>
<tr>
<td>4x2</td>
<td>100 MHz</td>
<td>87%</td>
</tr>
</tbody>
</table>

(4) The PCIe connection has a round-trip latency of 1250 ns. This latency puts a lower limit on modeled inter-node link latency. For example, at 100 MHz, the round-trip latency is equal to 125 cycles.

Most of these limits are not fundamental and are only dictated by the AWS infrastructure: the number of tiles per FPGA is limited by the FPGA size, the number of nodes per FPGA is limited by the number of DRAM slots per FPGA, and the number of FPGAs in a prototype is limited by the number of FPGAs in one F1 instance. The limits can be raised in the future if AWS updates its cloud FPGA infrastructure or other cloud providers introduce a larger selection of FPGAs.

We also want to note that SMAPPIC is not a total substitution for classic software simulators. Researchers often value flexibility over execution time, cost, or accuracy. FPGA emulation can be a poor fit in such situations because each system parameter’s change leads to complete prototype regeneration which can take hours. However, the use cases discussed above demonstrate situations where SMAPPIC is the users’ only real option due to its scale, speed, accuracy, and cost-efficiency.

5 RELATED WORK

5.1 FPGAs for Architecture Modeling

There are a few commercial tools for FPGA-accelerated design modeling, such as Cadence Palladium [13], Mentor Veloce [45], and Synopsys Zebu [55]. These systems are proprietary, have incredibly high prices (millions of dollars), and are not accessible to most researchers. SMAPPIC is open-source and uses a publicly available cloud infrastructure instead.

ProtoFlex [18] and FAST [15] use hardware to accelerate only the performance layer of the model. Some researchers propose using an FPGA to model only subparts of the whole system, e.g., memory subsystem [53] or NoC [26, 29]. In contrast, SMAPPIC models each node entirely inside the FPGA, making performance-accuracy tradeoffs more visible.

RAMP Gold [57], DIABLO [56], and HASim [40] put both performance and functional models into the FPGA. However, these frameworks use various techniques to pack more target logic inside a single FPGA at the cost of lower frequency. SMAPPIC uses direct gate-to-RTL mapping and keeps frequency as high as possible instead. SMAPPIC models large systems by partitioning across multiple FPGAs. Such a scaling strategy has good cost-efficiency in a cloud setting.
5.2 Multi-node System Modeling

PriME [23] supports the modeling of independent chips without any connectivity. MGPUSim [54] was designed specifically for multi-die modeling but only in the GPU domain. Sniper [14] supports modeling multi-die systems with shared memory but at much lower speeds than FPGAs. Unlike all these tools, SMAPPIC supports fast modeling of heterogeneous shared memory multi-node systems.

Enzian [20] and QuickIA [16] are similar to SMAPPIC in that they provide the foundation for building heterogeneous multi-chip prototypes. However, both frameworks use CPU + FPGA design where only the logic inside the FPGA can be modified. In contrast, SMAPPIC is fully customizable and can be changed by configuration options or modifying source code.

BYOC [10] and OpenPiton [9, 11] provide separate tools for multi-chip modeling and FPGA prototyping. However, they do not allow making FPGA prototypes of multi-chip architectures. Moreover, they support multi-chip capabilities only through a special hardware/software mechanism called Coherence Domain Restriction [22]. In contrast, SMAPPIC changes the original BYOC framework to provide multi-node capabilities out of the box without additional software modifications.

5.3 Multi-FPGA Architecture Modeling

FireSim [24] and DIABLO [56] support the modeling of multi-chip systems distributed over multiple FPGAs. However, they do it only without a unified memory, with different chips connected over Ethernet links. Unlike these tools, SMAPPIC provides coherent inter-node interconnect that tunnels existing inter-node interconnect through FPGA’s PCIe connection. This mechanism allows the modeling of multi-node systems with unified memory.

The Twinstar platform [6] can model the full 16-core Bluegene/Q compute chip but uses a local, sophisticated, expensive, and proprietary setup consisting of 60 FPGAs and can reach only speeds of 4 MHz. Moreover, the logic partition of the FPGAs in Twinstar was done manually by the engineers. SMAPPIC divides the design between FPGAs based on the user’s input and leverages the cloud infrastructure to free researchers from these complications.

5.4 Architecture Modeling in the Cloud and Its Cost Optimization

The FAME work [58] estimates the cost of software architecture simulation in the cloud. It concludes that running FPGA simulations on-prem is more cost-effective than running software simulations in the cloud. Our work makes much broader estimations and adds price calculations for cloud FPGA simulations and different types of software simulations.

The FireSim paper [24] compares the cost of cloud and on-premises FPGA simulation and concludes that large-scale simulations are financially sustainable only when using cloud infrastructure. Unlike SMAPPIC, FireSim is not compared with software simulators in terms of pricing.

5.5 Architecture Modeling in Cloud FPGAs

The main previous work on utilizing cloud FPGAs for architecture modeling is FireSim [24]. We consider SMAPPIC and FireSim two significantly different frameworks because they have different goals influencing their designs.

FireSim is designed from the ground up to be a datacenter simulator, and there is a big emphasis on simulating the network between separate nodes. This factor puts an additional restriction on the simulation speed and the size of separate computational nodes.

Unlike FireSim, SMAPPIC is designed to make the modeling of a separate system scalable. This goal allows SMAPPIC to scale prototypes up to large, 48-core, 4-node systems and be cost-effective when modeling small systems simultaneously. This result is achievable because we do not have the additional requirement of simulating IP network interactions.

6 CONCLUSION

This paper presents SMAPPIC – the first open-source prototype platform for shared memory multi-die architectures on cloud FPGAs. SMAPPIC achieves ease of use, cost-effectiveness, and multi-node scalability through modular, hierarchical, and parametrizable structure based on a cloud FPGA backend. By using BYOC’s infrastructure and AWS EC2 F1 instances, SMAPPIC provides a configurable underlying design that allows researchers to quickly and easily start using cloud-enabled FPGA prototypes.

SMAPPIC makes many unique use cases possible or significantly more accessible, in particular: large-scale multi-node architecture modeling, accelerator evaluation and verification, hardware/software co-development, in situ studies of custom architecture interaction with a cloud infrastructure, cost-efficient modeling, remote work, and education. We use SMAPPIC to build the first open-source multi-node 48-core 64-bit Linux-capable RISC-V system with unified memory and to make the first comparison of the architecture modeling methods’ costs in a cloud. SMAPPIC has the potential to enable even more exceptional studies in the future.

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